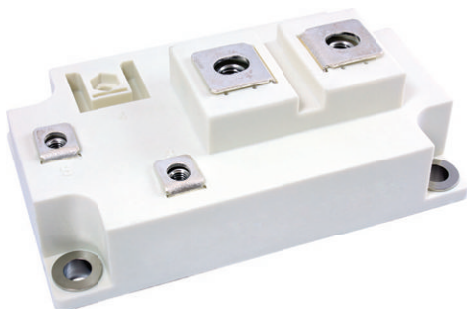


## Molding Type Module IGBT, 1-in-1 Package, 1200 V and 400 A



Double INT-A-PAK

### FEATURES

- 10  $\mu$ s short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- $V_{CE(on)}$  with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT

### PRODUCT SUMMARY

$V_{CES}$	1200 V
$I_C$ at $T_C = 80\text{ }^{\circ}\text{C}$	400 A
$V_{CE(on)}$ (typical) at $I_C = 400\text{ A}$ , $25\text{ }^{\circ}\text{C}$	3.10 V
Package	Double INT-A-PAK
Circuit	Single switch with AP diode

### TYPICAL APPLICATIONS

- Switching mode power supplies
- Inductive heating
- Electronic welder

### DESCRIPTION

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welder and inductive heating.

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		1200	V
Gate to emitter voltage	$V_{GES}$		$\pm 20$	
Collector current at $T_J = 150\text{ }^{\circ}\text{C}$	$I_C$	$T_C = 25\text{ }^{\circ}\text{C}$	550	A
		$T_C = 80\text{ }^{\circ}\text{C}$	400	
Pulsed collector current	$I_{CM}^{(1)}$	$T_C = 80\text{ }^{\circ}\text{C}$	800	
Diode continuous forward current	$I_F$		400	
Diode maximum forward current	$I_{FM}$		800	
Maximum power dissipation	$P_D$	$T_J = 150\text{ }^{\circ}\text{C}$	2841	W
Short circuit withstand time	$t_{SC}$	$T_J = 125\text{ }^{\circ}\text{C}$	10	$\mu$ s
RMS isolation voltage	$V_{ISOL}$	$f = 50\text{ Hz}$ , $t = 1\text{ min}$	2500	V

#### Note

<sup>(1)</sup> Repetitive rating: Pulse width limited by maximum junction temperature.

**IGBT ELECTRICAL SPECIFICATIONS** ( $T_C = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$T_J = 25\text{ }^{\circ}\text{C}$	1200	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}, I_C = 400\text{ A}, T_J = 25\text{ }^{\circ}\text{C}$	-	3.10	3.60	
		$V_{GE} = 15\text{ V}, I_C = 400\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$	-	3.45	-	
Gate to emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 4\text{ mA}, T_J = 25\text{ }^{\circ}\text{C}$	4.4	4.90	3.60	
Collector cut-off current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}, T_J = 25\text{ }^{\circ}\text{C}$	-	-	5.0	mA
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0\text{ V}, T_J = 25\text{ }^{\circ}\text{C}$	-	-	400	nA

**SWITCHING CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600\text{ V}, I_C = 400\text{ A}, R_g = 2.2\text{ }\Omega,$ $V_{GE} = \pm 15\text{ V}, T_J = 25\text{ }^{\circ}\text{C}$	-	680	-	ns
Rise time	$t_r$		-	142	-	
Turn-off delay time	$t_{d(off)}$		-	638	-	
Fall time	$t_f$		-	99	-	
Turn-on switching loss	$E_{on}$	$V_{CC} = 600\text{ V}, I_C = 400\text{ A}, R_g = 2.2\text{ }\Omega,$ $V_{GE} = \pm 15\text{ V}, T_J = 125\text{ }^{\circ}\text{C}$	-	19.0	-	mJ
Turn-off switching loss	$E_{off}$		-	32.5	-	
Turn-on delay time	$t_{d(on)}$		-	690	-	ns
Rise time	$t_r$		-	146	-	
Turn-off delay time	$t_{d(off)}$		-	669	-	
Fall time	$t_f$		-	108	-	
Turn-on switching loss	$E_{on}$	$V_{GE} = 0\text{ V}, V_{CE} = 30\text{ V}, f = 1.0\text{ MHz}$	-	26.1	-	mJ
Turn-off switching loss	$E_{off}$		-	36.7	-	
Input capacitance	$C_{ies}$		-	33.7	-	nF
Output capacitance	$C_{oes}$		-	2.99	-	
Reverse transfer capacitance	$C_{res}$		-	1.21	-	
SC data	$I_{SC}$	$t_p \leq 10\text{ }\mu\text{s}, V_{GE} = 15\text{ V}, T_J = 25\text{ }^{\circ}\text{C},$ $V_{CC} = 600\text{ V}, V_{CEM} \leq 1200\text{ V}$	-	2600	-	A
Internal gate resistance	$R_g$		-	0.5	-	$\Omega$
Stray inductance	$L_{CE}$		-	-	18	nH
Module lead resistance, terminal to chip	$R_{CC'+EE'}$	$T_C = 25\text{ }^{\circ}\text{C}$	-	0.32	-	m $\Omega$

**DIODE ELECTRICAL SPECIFICATIONS** ( $T_C = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode forward voltage	V <sub>F</sub>	I <sub>F</sub> = 400 A	T <sub>J</sub> = 25 °C	-	1.95	2.35	V
			T <sub>J</sub> = 125 °C	-	1.85	-	
Diode reverse recovery charge	Q <sub>rr</sub>	I <sub>F</sub> = 400 A, V <sub>R</sub> = 600 V, dI <sub>F</sub> /dt = - 2850 A/μs, V <sub>GE</sub> = - 15 V	T <sub>J</sub> = 25 °C	-	24.1	-	μC
	T <sub>J</sub> = 125 °C		-	44.3	-		
Diode peak reverse recovery current	I <sub>rr</sub>		T <sub>J</sub> = 25 °C	-	220	-	A
			T <sub>J</sub> = 125 °C	-	295	-	
Diode reverse recovery energy	E <sub>rec</sub>		T <sub>J</sub> = 25 °C	-	13.9	-	mJ
			T <sub>J</sub> = 125 °C	-	24.8	-	



# THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction temperature range	T <sub>J</sub>		-	-	150	°C
Storage temperature range	T <sub>Stg</sub>		- 40	-	125	°C
Junction to case per module	IGBT Diode R <sub>thJC</sub>		-	-	0.044	K/W
			-	-	0.088	
Case to sink	R <sub>thCS</sub>	Conductive grease applied	-	0.035	-	
Mounting torque		Power terminal screw: M5	2.5 to 5.0			Nm
		Mounting screw: M6	3.0 to 6.0			
Weight			300			g

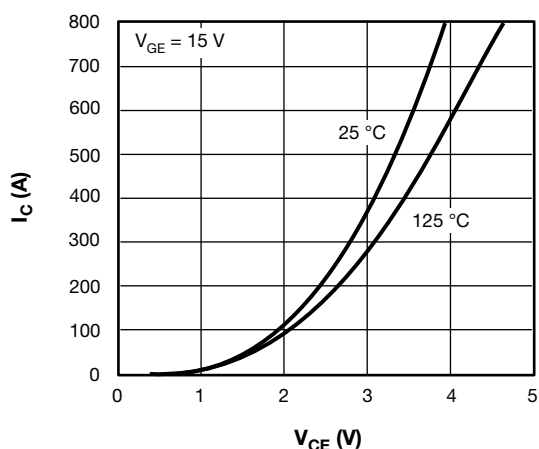


Fig. 1 - IGBT Typical Output Characteristics

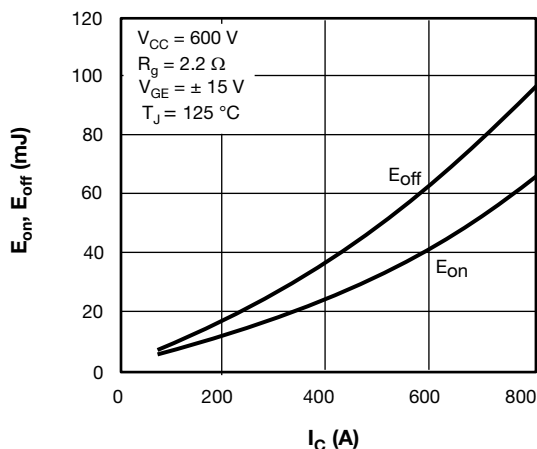


Fig. 3 - IGBT Switching Loss vs. Collector Current

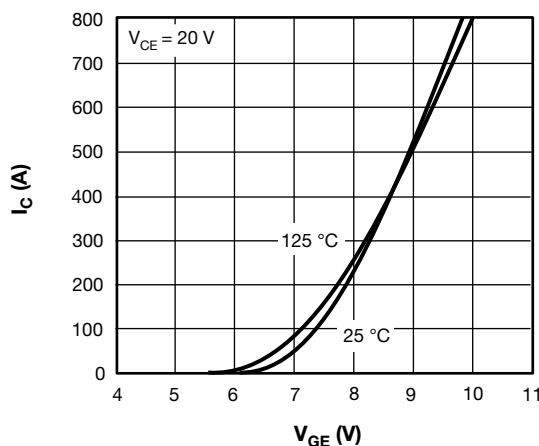


Fig. 2 - IGBT Typical Transfer Characteristics

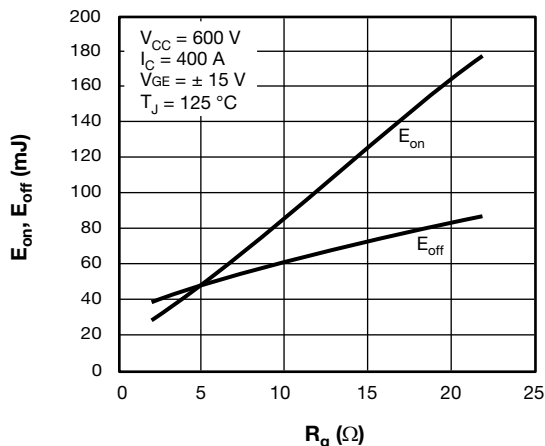


Fig. 4 - IGBT Switching Loss vs. Gate Resistor

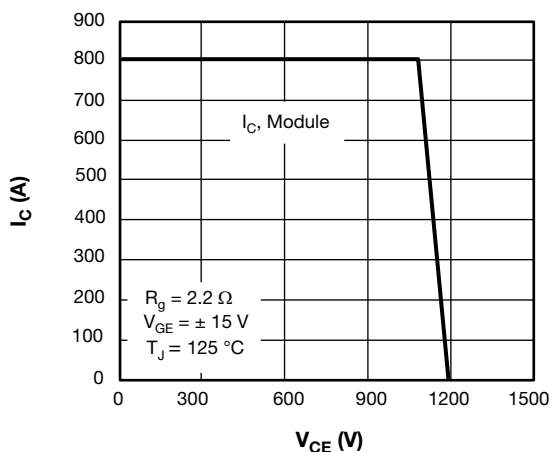


Fig. 5 - RBSOA

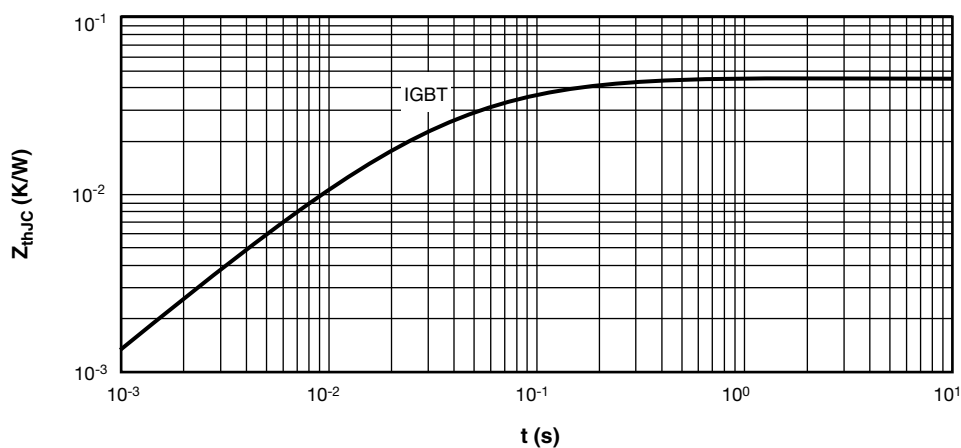


Fig. 6 - IGBT Transient Thermal Impedance

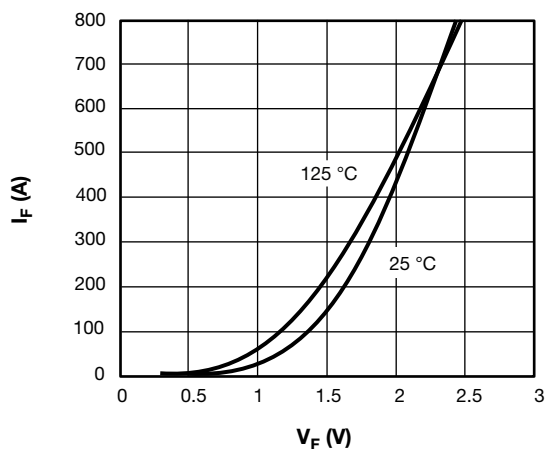
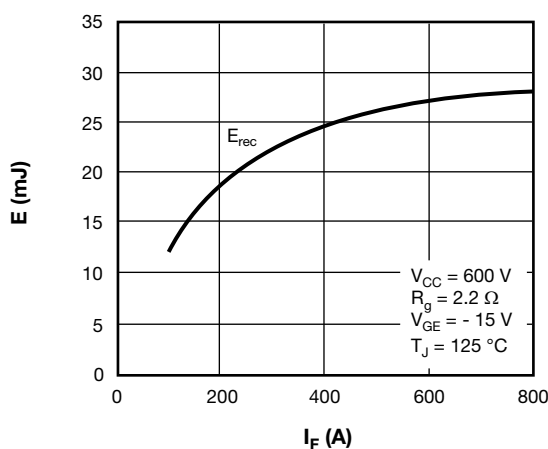


Fig. 7 - Diode Typical Forward Characteristics


Fig. 8 - Diode Switching Loss vs.  $I_F$

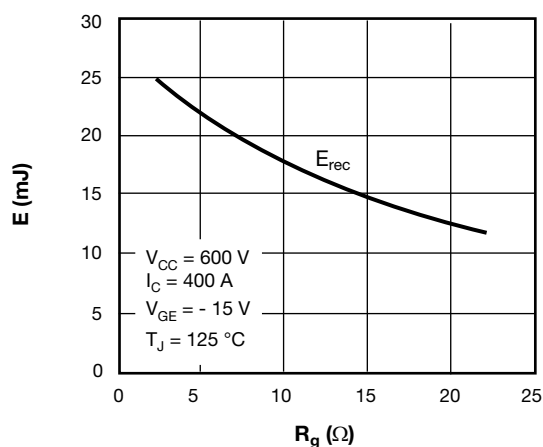
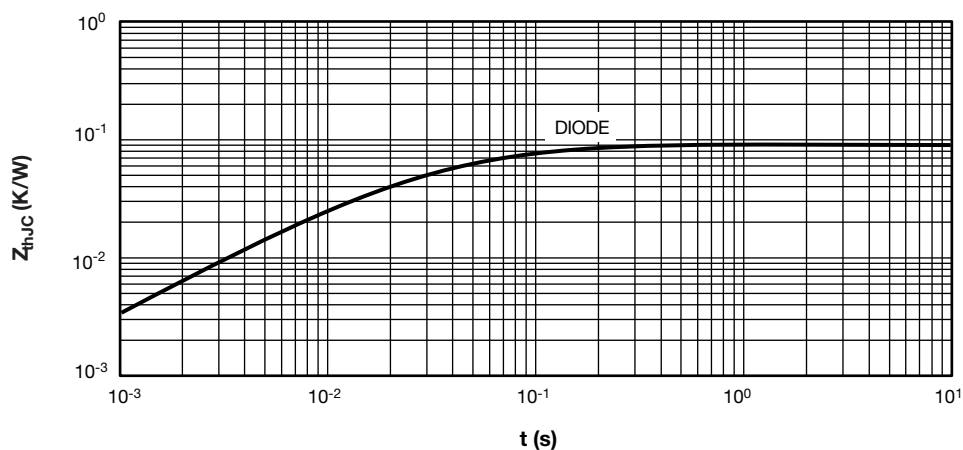
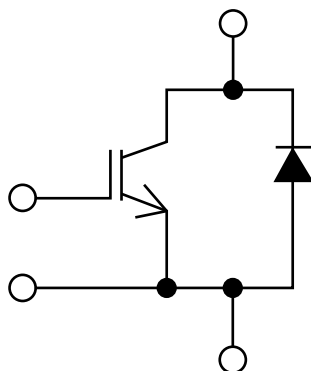

Fig. 9 - Diode Switching Loss vs.  $R_g$ 


Fig. 10 - Diode Transient Thermal Impedance

## CIRCUIT CONFIGURATION



### LINKS TO RELATED DOCUMENTS

Dimensions

[www.vishay.com/doc?95526](http://www.vishay.com/doc?95526)



## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**